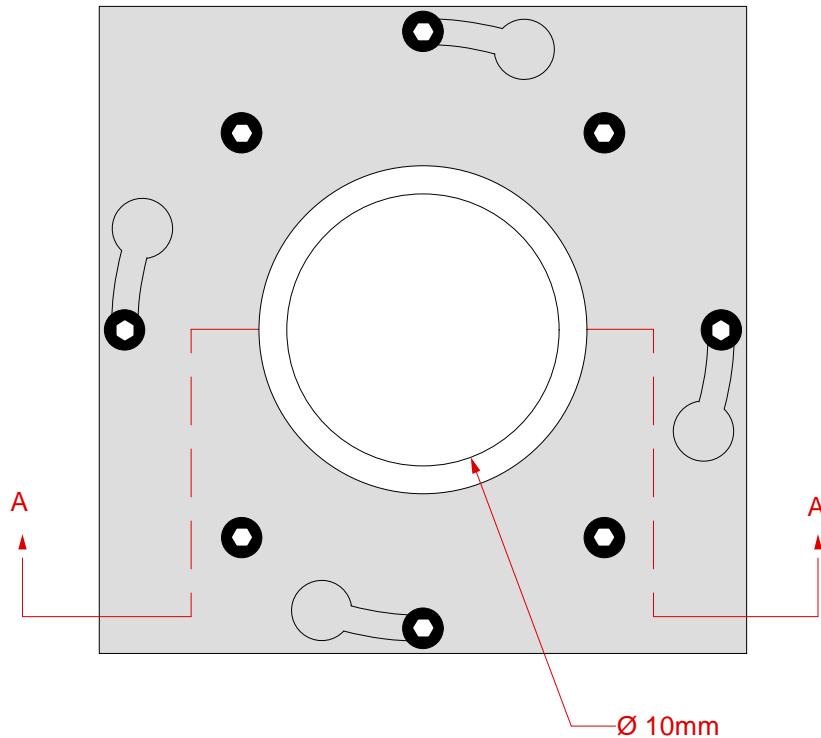


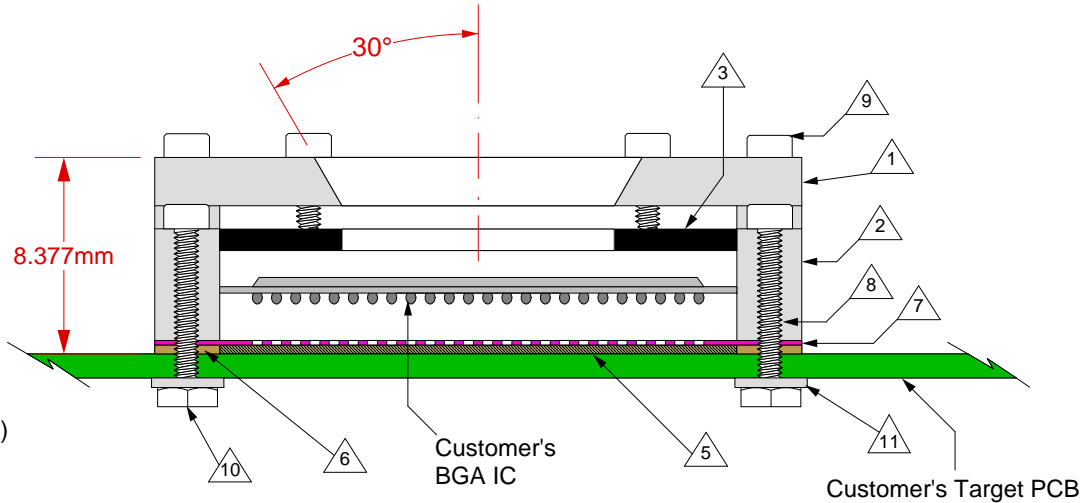
GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



Top View



Side View
(Section AA)

- △ 1 Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm.

- △ 2 Socket base: Black anodized Aluminum.
Thickness = 5mm.

- △ 3 Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm.

- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.75mm.

- △ 6 Elastomer Guide: Non-clad FR4.
Thickness = 0.75mm.

- △ 7 Ball Guide: Kapton polyimide.

- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.

- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.

- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.

- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD
0.64mm thickness.

SG-BGA-6054 Drawing

Status: Released

Scale: -

Rev: C



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Drawing: H. Hansen

Date: 7/29/02

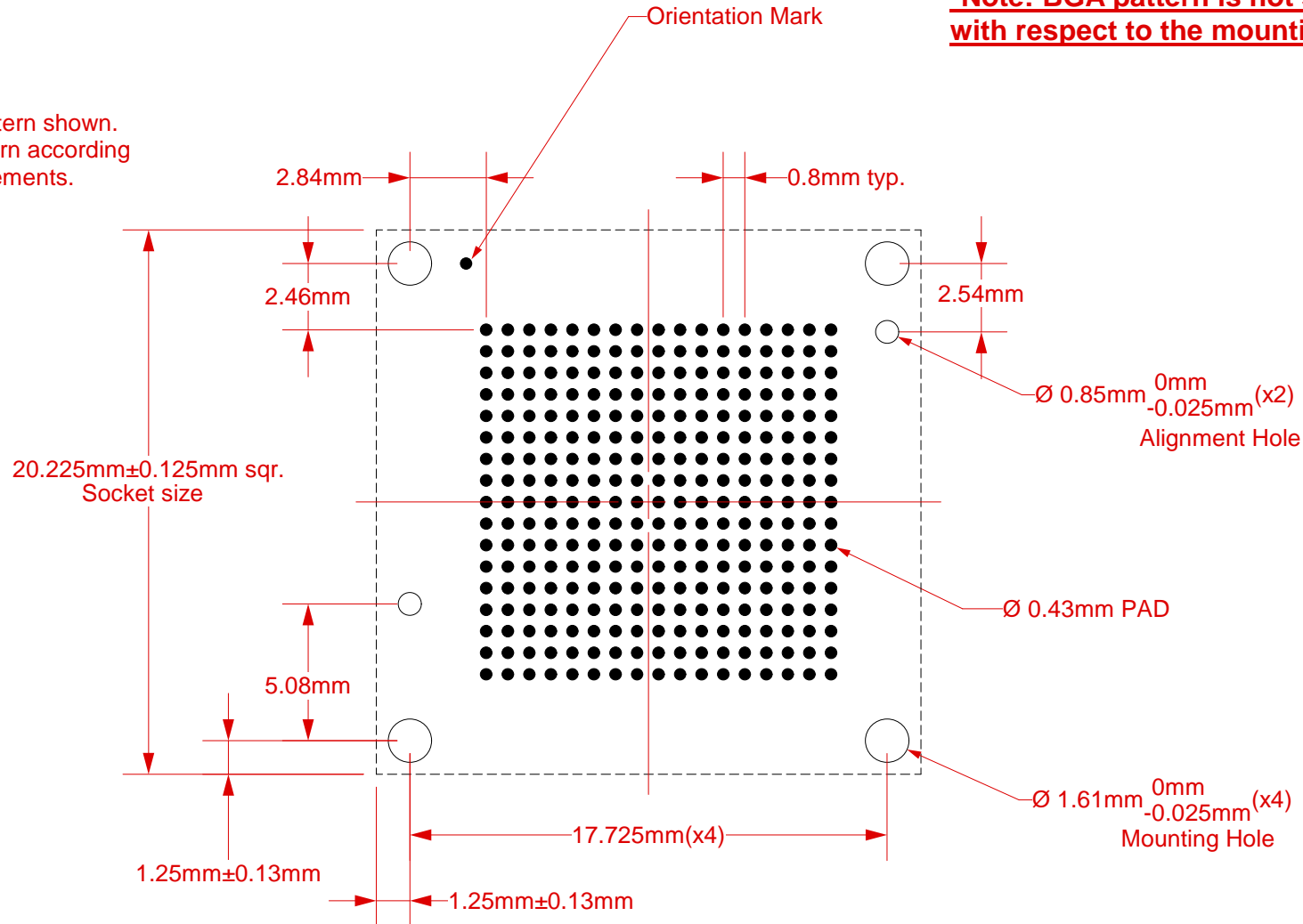
File: SG-BGA-6054 Dwg.mcd

Modified: 7/2/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.




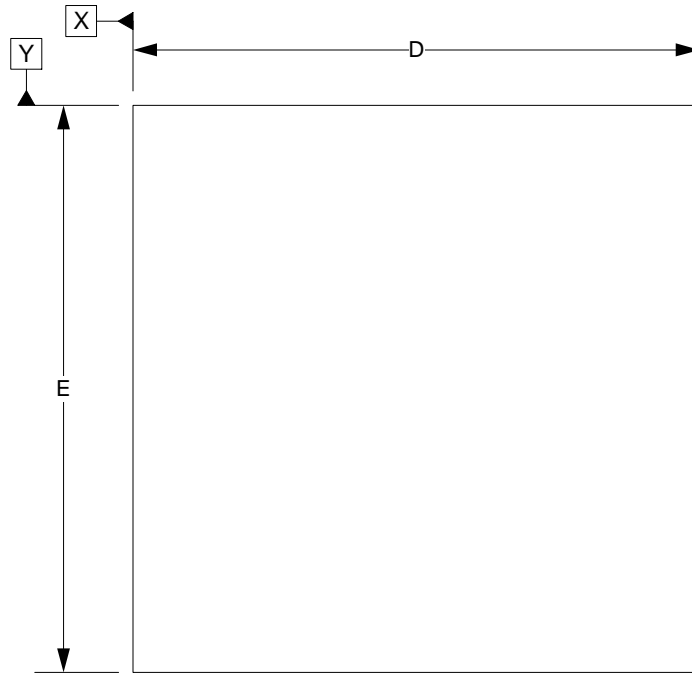
Target PCB Recommendations

Total thickness: 2.4mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

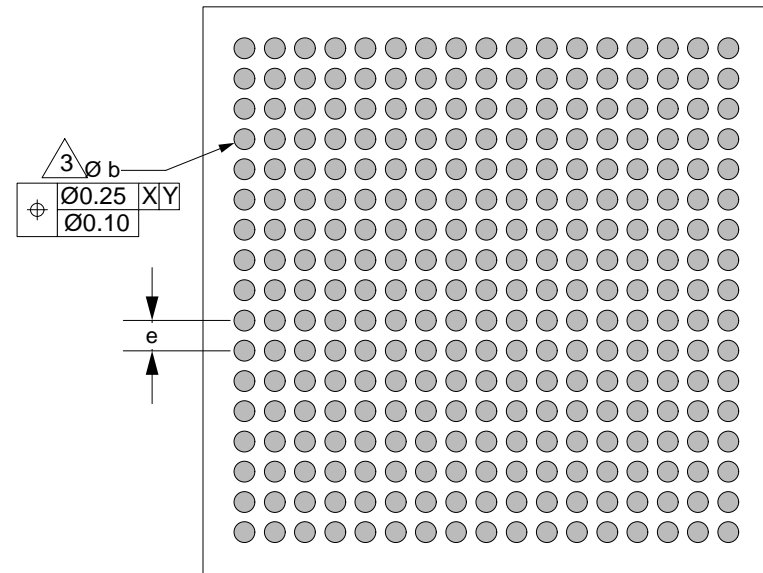
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

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	<p>Drawing: H. Hansen</p>	<p>Date: 7/29/02</p>		
	<p>File: SG-BGA-6054 Dwg.mcd</p>	<p>Modified: 7/2/09, AE</p>		

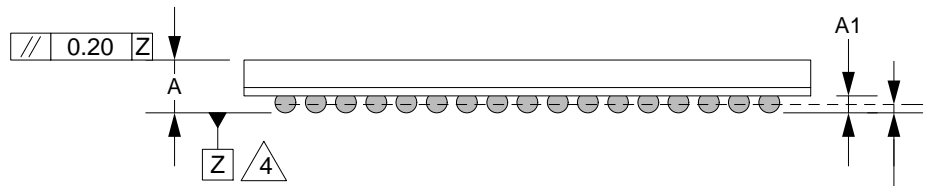


Top View



Bottom View

Array:17x17



Side View


1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.4
A1	0.35	0.45
b		0.55
D	15.0 BSC	
E	15.0 BSC	
e	0.8 BSC	

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	<p>Drawing: H. Hansen</p>	<p>Date: 7/29/02</p>		
	<p>File: SG-BGA-6054 Dwg.mcd</p>	<p>Modified: 7/2/09, AE</p>		